



PATENT

**In The United States Patent and Trademark Office**

In re Application of:

Assignee: Technologies and Devices International, Inc.

Inventors: Vladimir A. Dmitriev, *et al.*

Application No: 10/623,375

Filed: July 18, 2003

Title: Manufacturing Methods for Semiconductor Devices With Multiple III-V Material Layers

Docket No.: 700625-4001

Art Unit: 1765

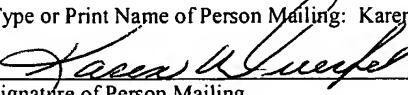
Examiner: Song, Matthew J.

**CERTIFICATE OF MAILING  
UNDER 37 CFR § 1.8**

Date of Deposit: March 29, 2005

I hereby certify that this paper and all enclosures are being deposited with the United States Postal Service as first class mail on the date indicated above in an envelope addressed to Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450.

Type or Print Name of Person Mailing: Karen Wuerfel

  
Signature of Person Mailing

**RESPONSE TO OFFICE ACTION**

Mail Stop Amendment  
Commissioner for Patents  
P. O. Box 1450  
Alexandria, Virginia 22313-1450

Commissioner:

In response to the Office Action mailed December 29, 2004, the Applicants respectfully submit the following remarks.